



Material Content Data Sheet



Sales Product Name		SAK-XC2723X-20F66V AA		Issued		26. September 2017			
MA#		MA001053290							
Package		PG-VQFN-48-54		Weight*		126.41 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	5.350	4.23	4.23	42325	42325	
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		140		
		non noble metal	zinc	7440-66-6	0.071	0.06		558	
		non noble metal	iron	7439-89-6	1.412	1.12		11168	
wire	non noble metal	copper	7440-50-8	57.319	45.35	46.54	453452	465318	
		noble metal	gold	7440-57-5	0.733	0.58	0.58	5802	5802
encapsulation	organic material	carbon black	1333-86-4	0.172	0.14		1359		
		plastics	epoxy resin	-	7.271	5.75		57522	
		inorganic material	silicondioxide	60676-86-0	49.810	39.40	45.29	394048	452929
leadfinish	non noble metal	tin	7440-31-5	2.340	1.85	1.85	18515	18515	
plating	noble metal	silver	7440-22-4	0.656	0.52	0.52	5189	5189	
glue	plastics	epoxy resin	-	0.288	0.23		2282		
		noble metal	silver	7440-22-4	0.966	0.76	0.99	7640	9922
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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